



TG-CJ-Li-60-60-15-PF Ceramic Heatsink

Version 3.220318

Ceramic Heatsink

T-Global's range of ceramic heatsinks have been designed from a proprietary blend of engineering ceramics to offer superior thermal management for the most demanding of applications. Compared to aluminium, ceramics confer additional benefits such as electrically isolating, resistant to corrosion, low weight and does not act like an antenna. The addition of a pre-applied thermal tape further reduces the manufacturing complexity when compared to aluminium heatsinks.

Features

- Large contact area
- Low weight
- High breakdown voltage
- Excellent heat spreader
- Custom shapes possible

Applications

LED, M/B, P/S, LCD, TV, Notebook, PC, PC Telecom Device, Wireless Hub, Power transistor, Power module, CPU, Chip IC

Properties

- ✓ REACH Compliant
- ✓ ROHS Compliant

Main Component		Technical Ceramic	
Property Type	Property	Unit	
Physical Property	Density	g/cm ³	3.66
	Water Absorption	%	0.002
	Sinter Temperature	°C	1700
	Acid Resistance	mg/cm ³	≤0.2
	Alkali	mg/cm ³	≤0.2
Mechanical Property	Mohs Hardness	HV	9
	Bend Strength	Mpa	≥ 610
	Compression Intensity	Mpa	≥ 620
Thermal Property	Maximum Working Temperature	°C	1400
	Thermal Expansion Coefficient	(1×10 ⁻⁶) mm/°C	7.8-8.3
	Thermal Shock Resistance	T (°C)	200
	Thermal Conductivity	W/m.k.	40-51
Electrical Property	Resisting Rate of Volume	Ω °C	1016
	DC Breakdown Strength	KV/mm	15.2-16.7
	Insulation Breakdown Intensity	KV/mm	18
	Dielectric Constant (1MHz)	(E)	10
	Dielectric Dissipation	(tg o)	0.4*10 ⁻³
Shelf Life of Tape	(can be requalified for further 12)	months	12

Part Number Information

Product	Length	Width	Depth	Adhesive
TG-CJ-Li-60-60-15-PF	60	60	15	1 Sided Tape

* All measurements in mm

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* Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

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